

Features

- 4 simultaneously sampled inputs
- Single 5V analog supply and 1.71 to 5V VDRIVE
- 16bit ADC with 350 ksps on all channels
- Bipolar inputs ranges: ±10V, ±5V
- Analog input clamp protection
- 1 MΩ analog input impedance
- On chip reference and buffer
- On chip oversampling digital filter
- SPI compatible interface
- Temperature range: -40°C to 125°C
- Package: LQFP10X10-64

Applications

- Power line monitor
- Power line protection relays
- Motor control
- Data acquisition system (DAS)
- Industrial Automation and controls

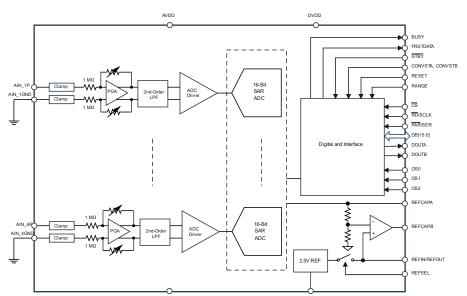
Description

TPAFE5161 is a 16bit, 4-channel simultaneous sampling, successive approximation (SAR) ADC. Each channel has a complete analog front end, as well as an ADC operating at 350 ksps per channel. The analog front end features input clamp, a programmable gain amplifier (PGA) with high input impedance of $1M\Omega$, low pass filter and ADC input driver.

The device features an internal precision reference with buffer to driver the ADC. A digital interface supports serial, parallel and parallel byte communication, which can be used with varies host controllers.

The TPAFE5161 can accept $\pm 10V$ or $\pm 5V$ true bipolar inputs with a single 5V supply. Also the high input impedance allows direct connection to transformers or other sensors without external driver circuits.

The zero latency conversion with high performance also makes the device suitable for industrial automation and control applications.



Typical Application Circuit



Product Family Table

Order Number	Input Range(V)	Package	
TPAFE5161SI04-QP7R	±10, ±5	LQFP10X10-64	



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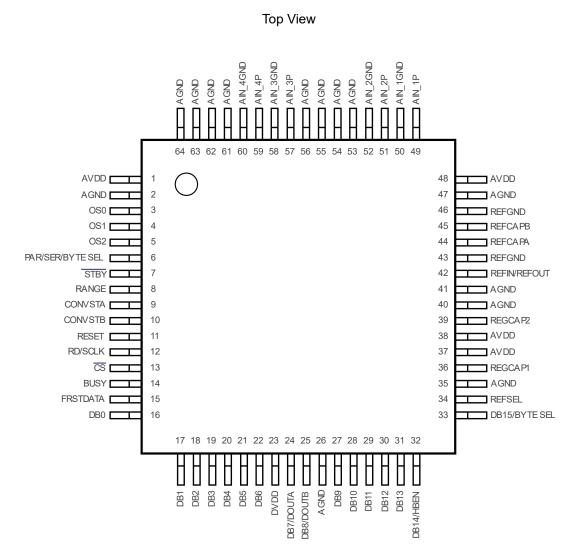


Revision History

Date	Revision	Notes	
2021-11-15	Rev.Pre.0	Pre-Release Version	
2022-3-1	Rev.Pre.1	Updated diagram and EC table	
2022-5-10	Rev.Pre.2	Updated EC table	
2022-5-22	Rev.Pre.3	Updated Tape and reel parameter	
2022-6-20	Rev.Pre.4	Updated EC table	
2023-5-1	Rev.Pre.5	Updated Timing Specifications and Timing Diagrams	
2023-8-1	Rev.A.0	Initial Released	



Pin Configuration and Functions



Pin Functions

	PIN		DESCRIPTION		
NO	Name	TYPE	DESCRIPTION		
1	AVDD	Р	Analog supply pin.		
2	AGND	Р	Analog ground pin.		
3	OS0	DI	Oversampling control pin.		
4	OS1	DI	Oversampling control pin.		
5	OS2	DI	Oversampling control pin.		
6	PAR/SER/BYTE SEL	DI	Control pin to select serial, parallel, or parallel byte interface mode.		
7	STBY	DI	Control pin to select standby or shutdown mode, active low.		



			Multi-function logic input pin:
			When STBY is low, this pin selects between the standby and shutdown modes.
8	RANGE	DI	When STBY is high, this pin selects input range ±10V or ±5V.
			Active high logic input to control start of conversion for first half count of device
9	CONVSTA	DI	input channels(Channel 1 and Channel 2)
			Active high logic input to control start of conversion for second half count of
10	CONVSTB	DI	device input channels(Channel 3 and Channel 4)
11	RESET	DI	Active high logic input to reset the device digital logic
			Multi-function logic input pin:
			this pin is active-low ready input pin in parallel and parallel byte interface;
12	RD/SCLK	DI	this pin is clock input pin in serial interface mode.
13	CS	DI	Active low logic input chip-select signal
14	BUSY	DO	Active high digital output indicating ongoing conversion
15	FRSTDATA	DO	Active high digital output indicating data read back from channel 1 of the device
16	DB0	DO	Data output DB0 (LSB) in parallel interface mode
17	DB1	DO	Data output DB1 in parallel interface mode
18	DB2	DO	Data output DB2 in parallel interface mode
19	DB3	DO	Data output DB3 in parallel interface mode
20	DB4	DO	Data output DB4 in parallel interface mode
21	DB5	DO	Data output DB5 in parallel interface mode
22	DB6	DO	Data output DB6 in parallel interface mode
23	DVDD	Р	Digital supply pin; decouple with AGND on pin 26.
			Multi-function logic output pin:
			this pin is data output DB7 in parallel and parallel byte interface mode;
24	DB7/DOUTA	DO	this pin is a data output DB7 in parallel and parallel byte interface mode,
24	DBI/DOUTA	00	this pin is a data output pin in senai interface mode.
			Multi-function logic output pin:
			this pin is data output DB8 in parallel and parallel byte interface mode;
25	DB8/DOUTB	DO	this pin is a data output pin in serial interface mode.
26	AGND	Р	Analog ground pin.
27	DB9	DO	Data output DB9 in parallel interface mode
28	DB10	DO	Data output DB10 in parallel interface mode
29	DB11	DO	Data output DB11 in parallel interface mode
30	DB12	DO	Data output DB12 in parallel interface mode
31	DB13	DO	Data output DB13 in parallel interface mode
_ <u> </u>	•		······································



			Multi function logic input or output ning
			Multi-function logic input or output pin:
			this pin is data output DB14 in parallel interface mode;
32	DB14/HBEN	DO	this pin is a control input pin for byte selection (high or low) in parallel byte
32	UD14/NDEN	00	interface mode
			Multi-function logic input or output pin:
			this pin is data output DB15 (MSB) in parallel interface mode;
33	DB15/BYTE SEL	DO	this pin is an active high control input pin to enable parallel byte interface mode.
34	REFSEL	DI	Active high logic input to enable the internal reference
35	AGND	Р	Analog ground pin.
			Output pin 1 for the internal voltage regulator; decouple separately to AGND
36	REGCAP1	AO	using a 1-µF capacitor. Typical 4V.
37	AVDD	Р	Analog supply pin.
38	AVDD	Р	Analog supply pin.
			Output pin 2 for the internal voltage regulator; decouple separately to AGND
39	REGCAP2	AO	using a 1-µF capacitor. Typical 4V.
40	AGND	Р	Analog ground pin.
41	AGND	Р	Analog ground pin.
			This pin acts as an internal 2.5V reference output when REFSEL is high;
			this pin functions as input pin for the external reference when REFSEL is low;
42	REFIN/REFOUT	AIO	decouple with REFGND on pin 43 using a $10-\mu$ F capacitor.
72			Reference GND pin. This pin must be shorted to the analog GND plane and
			decoupled with
43	REFGND	Р	REFIN/REFOUT on pin 42 using a 10-µF capacitor.
			Reference amplifier output pins. This pin must be shorted to REFCAPB and
44	REFCAPA	AO	decoupled to AGND using a low ESR, 10-µF ceramic capacitor. Typical 4V.
45			Reference amplifier output pins. This pin must be shorted to REFCAPA and
45	REFCAPB	AO	decoupled to AGND using a low ESR, 10-μF ceramic capacitor. Typical 4V.
			Reference GND pin. This pin must be shorted to the analog GND plane and
46	REFGND	Р	decoupled with
	_	P	REFIN/REFOUT on pin 42 using a 10-µF capacitor.
47	AGND		Analog ground pin.
48 49	AVDD	P AIO	Analog supply pin. Analog input channel 1: positive input
49 50	AIN_1P AIN_1GND	AIO	Analog input channel 1: negative input
50 51	AIN_1GND AIN_2P	AIO	Analog input channel 1: negative input Analog input channel 2: positive input
51	AIN_2P AIN_2GND	AIO	Analog input channel 2: negative input
52	AIN_2GND AGND	P	Analog ground pin.
53 54	AGND	P P	
			Analog ground pin.
55	AGND	Р	Analog ground pin.



56	AGND	Р	Analog ground pin.	
57	AIN_3P	AIO	Analog input channel 3: positive input	
58	AIN_3GND	AIO	Analog input channel 3: negative input	
59	AIN_4P	AIO	Analog input channel 4: positive input	
60	AIN_4GND	AIO	Analog input channel 4: negative input	
61	AGND	Р	Analog ground pin.	
62	AGND	Р	Analog ground pin.	
63	AGND	Р	Analog ground pin.	
64	AGND	Р	Analog ground pin.	



Specifications

Absolute Maximum Ratings

At T_A=25°C

	Parameter	Min	Мах	Unit
	AVDD to AGND	-0.3	7	V
	DVDD to DGND	-0.3	7	V
	AGND to DGND	-0.3	0.3	V
	Analog input voltage to AGND	-15	15	V
	Digital input to DGND	-0.3	DVDD + 0.3	V
	REFIN to AGND	-0.3	AVDD + 0.3	V
Inpu	it current to any pin except supplies	-10	10	mA
TJ	Maximum Junction Temperature	-40	150	°C
T _A	T _A Operating Temperature Range		125	°C
Tstg	T _{STG} Storage Temperature Range		150	°C
ΤL	Lead Temperature (Soldering 10 sec)		260	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

(2) This data was taken with the JEDEC low effective thermal conductivity test board.

(3) This data was taken with the JEDEC standard multilayer test boards.

ESD, Electrostatic Discharge Protection

Symbol	Parameter	Parameter Condition		Unit
HBM	Human Body Model ESD for all pins except analog input pins	ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±5000	V
НВМ	Human Body Model ESD for analog input pins only	ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±7000	V
CDM	Charged Device Model ESD	ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

Recommended Operating Conditions

Para	Min	Тур	Мах	Unit	
AVDD Analog supply voltage		4.75	5	5.25	V
DVDD	DVDD Digital supply voltage		3.3	AVDD	V

Thermal Information

Package Type	Package Type $ extbf{ heta}_{JA}$		Unit	
LQFP10X10-64	46	7.8	°C/W	



Electrical Characteristics

All test conditions: $V_{REF}=2.5V$ external/internal, AVDD = 4.75V to 5.25V, $V_{DRIVE}=1.71V$ to AVDD, $f_{SAMPLE}=350$ ksps, $T_A=-40^{\circ}C$ to 125°C, Low Bandwidth Mode, unless otherwise noted.

Symbol	Parameter	Test condition		MIN	ТҮР	МАХ	Unit
Dynamic Perfo	ormance						
		fin=1kHz sine wave,	±10V No oversampling	86	89.7		dB
	Signal to noise	unless otherwise noted	±5V No oversampling	85.5	89.5		dB
SNR	ratio	fin=130Hz	Oversampling by 16, ±10V Range	91	95.2		dB
		fin=130Hz	Oversampling by 16, ±5V Range	91	94.7		dB
	Signal to noise	fin=1kHz sine wave,	±10V No oversampling		89.5		dB
SINAD	+ distortion ratio	unless otherwise noted	±5V No oversampling		89.4		dB
THD	Total harmonic distortion	All input range, fin=1KHz			-106		dB
SFDR	Spurious free dynamic range	fin=1KHz			-106		dB
Analog Input F	Filter	_			-		
		Low Bandwidth Mode	-3dB, ±10V		20.0		KHz
	Small signal	Low Bandwidth Mode	-3dB, ±5V		12.7		KHz
BW(-3 dB)	bandwidth	High Bandwidth Mode	-3dB, ±10V		26.5		KHz
		High Bandwidth Mode	-3dB, ±5V		16.4		KHz



16bit,	4-Channel,	Simultaneous	Sampling A	٩DC
		with	Bipolar inp	uts

$ \begin{tabular}{ c c c c c } & & & & & & & & & & & & & & & & & & &$			Low					
$ \begin{tabular}{ c c c c } \hline c c c c c c c c c c c c c c c c c c $				-0.1dB. ±10V		3.3		KHz
$ \begin{split} & \text{BW}(-0.1 \mathrm{dB}) \\ & \text{Small signal bandwidth} & \text{burker bandwidth} & burke$, -				
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$\begin{array}{c c c c c c c } & Sinal signal bandwidth bandwidth bandwidth & High Bandwidth & -0.1dB, \pm10V & A.3 & KHz & KHz & Mode & A.3 & KHz & High Bandwidth & -0.1dB, \pm5V & A.3 & KHz & High Bandwidth & \pm10V & A.3 & A.3 & KHz & High Bandwidth & \pm10V & A.3 & A.3 & KHz & High Bandwidth & \pm10V & A.3 & A.3 & KHz & High Bandwidth & \pm10V & A.3 & A$				-0.1dB, ±5V		2.2		KHz
$\begin{array}{ c c c c c c c } & High & $		Small signal						
$\begin{array}{c c c c c c c } & & & & & & & & & & & & & & & & & & &$	BW(-0.1 dB)	-	High					
$\begin{array}{ c c c c } & & & & & & & & & &$			-	-0.1dB, ±10V		4.3		KHz
$ \begin{array}{ c c c c } & Bandwidth & -0.1dB, \pm 5V & & & & & & & & & & & & & & & & & & $			Mode					
$ \begin{array}{ c c c c } & Bandwidth & -0.1dB, \pm 5V & & & & & & & & & & & & & & & & & & $			High					
$ \begin{array}{c c c c c c } Int & Int &$			_	-0.1dB, ±5V		2.6		KHz
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$\begin{array}{c c c c c c c } Tgroup_delay & Group delay & Low & Bandwidth & \pm5V & 16 & 16 & us \\ & & & & & & & & & & & & & & & & & & $			Bandwidth	±10V		10		us
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$\frac{\text{DNL}}{\text{Integral}} = \frac{1.5}{1.5} + 1$		Differential	f _{SAMPLE} =	: 350 ksps,				
$\frac{1}{1000} = \frac{1}{1000} + \frac{1}{1000} + \frac{1}{1000} + \frac{1}{10000} + \frac{1}{10000000000000000000000000000000000$	DNL		-40	~85°C	-0.99	±0.5	1.5	LSB
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INL Integral nonlinearity $f_{SAMPLE} = 350 \text{ kSPS},$ $-40 \sim 85^{\circ}\text{C}$ ± 1 ± 2.5 LSB ± 1 \pm			fsample =	200 kSPS,				
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Image: Scale Error -40~85°C Image: Scale Error Ext Image: Scale Error Image: Scale Error Image: Scale Error Image: Scale Error		nonlinearity		350 kSPS,			. –	
Positive and Negative Full reference ±4 ±50 LSB Scale Error Int +15 LSB			-40	~85°C		±1	±2.5	LSB
Negative Full reference Scale Error Int			Ext					
Scale Error Int +15 ISB			reference			±4	±50	LSB
Scale Error LSB		-	Int					
reference		Scale Error	reference			±15		LSB



16bit,	4-Channel,	Simultaneous	Sampling ADC	
		with	Bipolar inputs	

					1		
	Positive Full	Ext reference			±2		ppm/C
	Scale Error Drift	Int reference			±10		ppm/C
	Negative Full	Ext reference			±2		ppm/C
	Scale Error Drift	Int reference			±10		ppm/C
	Bipolar Zero		±10V		±1	±15	LSB
	Code Error		±5V				
	Bipolar Zero		±10V		±10		μV/C
	Code Error Drift		±5V		±5		μV/C
	Bipolar Full Scale Error Matching				±6	±22	LSB
	Bipolar Zero Code Error matching		±5V ±10V		±3	±20	LSB
Analog Input	<u> </u>		I				
	Input Range	Vx-VxGND	RANGE=1, ±10V range	-10		10	- v
			RANGE=0, ±5V range	-5		5	
	Analog Input		10V range		(Vin-2)/Rin		uA
	Current		5V range		(11-2)/11		uA
CIN	Input capacitance				5		pF
R _{IN}	Input resistance				1		Mohm
Input Impedance Drift	Input Impedance Drift				±20		ppm/C
Reference inp	ut/output						
	Reference input voltage	REF SELECT=0, select Ext Ref, force voltage on REFIN/REFOUT		2.475	2.5	2.525	V
	Reference output voltage	REF_SELECT=1, REFIN/REFOUT output voltage T _A =25°C		2.495	2.5	2.505	V
	Reference voltage TC				±10		ppm/C



16bit, 4-Channel,	Simultaneous	Sampling	ADC
	with	Bipolar in	puts

	1					1	r
		Voltage on I	REFCAPA and				
	V(REFCAPA/B)	REFCAPB, also used for ADC			4		V
LOGIC INPUT							
VIH	Input high	input logic		0.7*VDRIVE			V
VIH	voltage	high voltage					v
VIL	Input low	input logic				0.3*VDRIVE	V
VIL	voltage	low voltage				0.5 VDINIVE	v
Cı	Input	input			5		pF
Ci	capacitance	capacitance			5		μr
I,	Input current	input				<u>+2</u>	uA
"	input current	current				<u>+</u> 2	uA
LOGIC OUTPU	Т						
Vон	Output high		current	VDRIVE-0.2			V
VOH	voltage		source=100uA	VDRIVE-0.2			V
V _{OL}	Output low		current			0.2	V
VOL	voltage		sink=100uA			0.2	v
	Float state				±1	120	
	leakage current				±I	±20	uA
Co	Output				5		pF
Co	capacitance				5		рг
Conversion ra	te						
	conversion time				3.5		us
	Acquisition				1 5		
	Time				1.5		us
	Throughput	Derekernel				200	kSPS
	Rate	Per channel				200	KOPO
Timing specifi	cations						
			VDRIVE>2.7V			23.5	MHz
	frequency of						
SCLK	serial interface						
	Senai interiace						
			VDRIVE>1.7V			15	MHz



AVCC normal		41	51	mA
AVCC Stanby		5	9	mA
AVCC Shutdown		11	25	uA

(1) 100% tested at $T_A = 25^{\circ}C$.



Timing Specifications

AV_{CC} = 5 V, V_{DRIVE} =1.7 V to 5.5 V, V_{REF} = 2.5 V, T_A = T_{MIN} to T_{MAX}

Parameter		TMIN, TMA and 0.9 x Input Le		Unit	Description
	Min	Тур	Мах		
PARALLEL/SERIAL/BYTE M	IODE	1	1	1	
t _{CYCLE}					1/throughput rate
		2.85		μs	Parallel mode, reading during or after conversion; or serial mode:
					V_{DRIVE} = 2.7 V to 5.5 V, reading during a conversion using $D_{\text{OUT}}A$
					and D _{OUT} B lines
		4.5		μs	Serial mode: $V_{\text{DRIVE}}\text{=}$ 2.7 V, reading after a conversion using $D_{\text{OUT}}A$
					and D _{out} B lines
		6		μs	Serial mode: $V_{\text{DRIVE}}\text{=}$ 1.7 V, reading after a conversion using $D_{\text{OUT}}A$
					and D _{OUT} B lines
t _{CONV}					Conversion time
		1.74		μs	Oversampling off;
		4.4		μs	Oversampling by 2;
		9.6		μs	Oversampling by 4;
		20		μs	Oversampling by 8;
		41		μs	Oversampling by 16;
		83		μs	Oversampling by 32;
		167		μs	Oversampling by 64;
twake-up standby		100		μs	STBY rising edge to CONVST x rising edge; power-up time from standby mode
twake-up shutdown					
Internal Reference		180		ms	STBY rising edge to CONVST x rising edge; power-up time from shutdown mode
External Reference		13		ms	STBY rising edge to CONVST x rising edge; power-up time from shutdown mode
t _{RESET}		100		ns	RESET high pulse width
t ₁		40		ns	CONVST x high to BUSY high
t ₂	25			ns	Minimum CONVST x low pulse
t ₃	25			ns	Minimum CONVST x high pulse
t4	45			ns	BUSY falling edge to $\overline{\text{CS}}$ falling edge setup time
t ₅		0.5		ms	Maximum delay allowed between CONVST A, CONVST B rising edges
t ₆	110			ns	Minimum time between last \overrightarrow{CS} rising edge and BUSY falling edge



16bit, 4-Channel	, Simultaneous	Sampling ADC
	with	Bipolar inputs

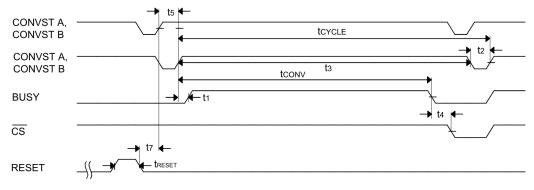
t ₇	25		ns	Minimum delay between RESET low to CONVST x high
PARALLEL/BYTE	READ OPERATION			
t ₈	0		ns	CS to RD setup time
t ₉	0		ns	CS to RD hold time
t ₁₀				RD low pulse width
	22		ns	V _{DRIVE} above 2.7 V
	32		ns	V _{DRIVE} above 1.7 V
t ₁₁	10		ns	RD high pulse width
t ₁₂	10		ns	CS high pulse width; CS and RD linked
t ₁₃				Delay from CS until DB[15:0] three-state disabled
		21	ns	V _{DRIVE} above 2.7 V
		30	ns	V _{DRIVE} above 1.7 V
t ₁₄				Data access time after RD falling edge
		21	ns	V _{DRIVE} above 2.7 V
		30	ns	V _{DRIVE} above 1.7 V
t ₁₅	6		ns	Data hold time after RD falling edge
t ₁₆	6		ns	CS to DB[15:0] hold time
t ₁₇		20	ns	Delay from \overline{CS} rising edge to DB[15:0] three-state enabled
SERIAL READ OPE	RATION		1	
f _{SCLK}				Frequency of serial read clock
		23.5	MHz	V _{DRIVE} above 2.7 V
		15	MHz	V _{DRIVE} above 1.7 V
t ₁₈				Delay from \overline{CS} until $D_{OUT}A/D_{OUT}B$ three-state disabled/delay from
				CS until MSB valid
		10	ns	V _{DRIVE} above 2.7 V
		15	ns	V _{DRIVE} above 1.7 V
t ₁₉				Data access time after SCLK rising edge
		21	ns	V _{DRIVE} above 2.7 V
		30	ns	V _{DRIVE} above 1.7 V
t ₂₀	0.4tsclk		ns	SCLK low pulse width
t ₂₁	0.4t _{SCLK}		ns	SCLK high pulse width
t ₂₂	6		ns	SCLK rising edge to $D_{OUT}A/D_{OUT}B$ valid hold time
t ₂₃		15	ns	\overline{CS} rising edge to $D_{OUT}A/D_{OUT}B$ three-state enabled
FRSTDATA OPERA	TION	· · ·	·	·
t ₂₄				Delay from CS falling edge until FRSTDATA three-state disabled
		11	ns	V _{DRIVE} above 2.7 V
	1 1	1	1	V _{DRIVE} above 1.7 V



16bit,	4-Channel,	Simultaneous	Sampling ADC
		with	Bipolar inputs

t ₂₅			Delay from \overline{CS} falling edge until FRSTDATA high, serial mode
	11	ns	V _{DRIVE} above 2.7 V
	20	ns	V _{DRIVE} above 1.7 V
t ₂₆			Delay from \overline{RD} falling edge to FRSTDATA high
	22	ns	V _{DRIVE} above 2.7 V
	32	ns	V _{DRIVE} above 1.7 V
t ₂₇			Delay from RD falling edge to FRSTDATA low
	22	ns	V _{DRIVE} above 2.7 V
	32	ns	V _{DRIVE} above 1.7 V
t ₂₈			Delay from 16 th SCLK falling edge to FRSTDATA low
	22	ns	V _{DRIVE} above 2.7 V
	32	ns	V _{DRIVE} above 1.7 V
t ₂₉	20	ns	Delay from \overline{CS} rising edge until FRSTDATA three-state enabled

Timing Diagrams





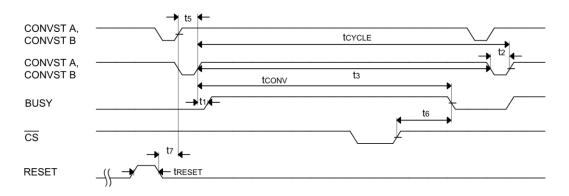


Figure 2. CONVST Timing—Reading During a Conversion



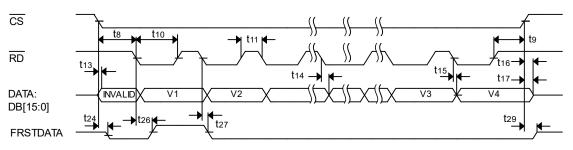


Figure 3. Parallel Mode, Separate \overline{CS} and \overline{RD} Pulses

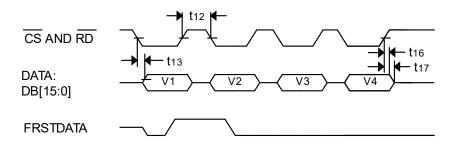


Figure 4. \overline{CS} and \overline{RD} , Linked Parallel Mode

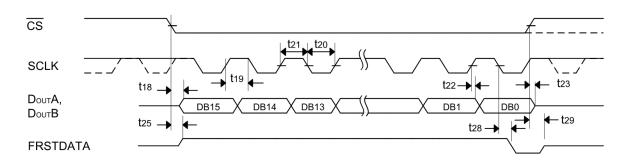


Figure 5. Serial Read Operation (Channel 1)

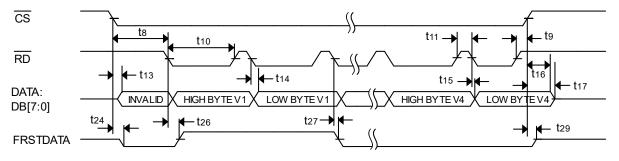


Figure 6. BYTE Mode Read Operation



Detailed Description

Overview

TPAFE5161 is a 16bit, 4-channel simultaneous sampling, successive approximation (SAR) ADC. Each channel has a complete analog front end, as well as an ADC operating at 350 ksps per channel. The analog front end features input clamp, a programmable gain amplifier (PGA) with high input impedance of $1M\Omega$, low pass filter and ADC input driver.

The device features an internal precision reference with buffer to driver the ADC. A digital interface supports serial, parallel and parallel byte communication, which can be used with varies host controllers.

The TPAFE5161 can accept $\pm 10V$ or $\pm 5V$ true bipolar inputs with a single 5V supply. Also the high input impedance allows direct connection to transformers or other sensors without external driver circuits.

Feature Description

Analog inputs

The TPAFE5161 has 4 analog input channels, and positive inputs AIN_nP (n = 1 to 4) are the single ended analog inputs and the negative inputs AIN_nGND should be tied to GND.

The input voltage range can be configured to bipolar ± 10 V or ± 5 V by the RANGE pin.

The device allows a ±0.3-V range on the AIN_nGND

Analog input impedance

Each analog input channel in the device presents a constant resistive impedance of 1 M Ω . Matching the external source impedance on the AIN_*n*P input pin with an equivalent resistance on the AIN_*n*GND pin is recommended to cancel any additional offset error contributed by the external resistance.

Input Clamp Protection Circuit

The input clamp protection circuit allows analog input to swing up to ± 30 V (typical). The input clamp circuit turns on beyond clamp voltage.

For input voltages above the clamp threshold, make sure that input current never exceeds the absolute maximum rating to prevent any damage to the device.

Don't keep the device in a state such that the clamp circuit is activated for extended periods of time, because this fault condition can degrade device performance and reliability.

Programmable Gain Amplifier (PGA)

The device has a programmable gain amplifier (PGA) at each individual input channel. The PGA converts the single-ended input signal into a fully-differential signal to drive internal ADC. The PGA also adjusts the common-mode voltage feeding into the ADC to ensure maximum usage of the ADC input dynamic range. The PGA gain is adjusted by configuring the RANGE pin of the ADC accordingly.

Low Pass Filter

Each channel of the TPAFE5161 features a second-order antialiasing low pass filter (LPF) at the output of the PGA, to remove the noise of the front-end amplifiers and gain resistors of the PGA.

ADC Driver



There is an integrated ADC input driver before each ADC channel. This integrated ADC driver eliminates the need any external amplifier, helping inputs of the ADC to settle to better than 16-bit accuracy before any sampled analog voltage gets converted. And thus the signal chain design for the user is simplified. **Digital filter**

The TPAFE5161 has an optional digital averaging filter that can be used in slower throughput applications requiring lower noise and higher dynamic range. The oversampling ratio of the digital filter is determined by the configuration of the OS[2:0] pins.

In oversampling mode, the samples are averaged to reduce the noise of the signal chain as well as to improve the SNR of the ADC. The final output is also decimated to provide data for each channel.

		MAX THROUGHPUT		
OS[2:0]	OS RATIO	PER CHANNEL		
		(kSPS)		
000	NO OS	350		
001	2	175		
010	4	87.5		
011	8	43.75		
100	16	21.875		
101	32	10.94		
110	64	5.47		
111	NA	350		

Reference

The TPAFE5161 can operate with either an internal voltage reference or an external voltage reference. The internal or external reference selection is determined by an external REFSEL pin,

The REFIN/REFOUT pin outputs the internal band-gap voltage (in internal reference mode) or functions as input pin to the external reference voltage (in external reference mode). The on-chip amplifier is enabled in both modes to drive the actual reference input of the internal ADC core. The REFCAPA and REFCAPB pins must be shorted together externally and a ceramic capacitor of minimum 10 µF should be connected between this node and REFGND to ensure that the internal reference buffer is operating as closed loop.

ADC transfer function

The TPAFE5161 outputs 16 bits data in binary twos complement format for both bipolar input ranges. The format for the output codes is the same across all analog channels.

Input range(V)	Full scale Range(V)	LSB(µV)
± 10	20	305.18
± 5	10	152.59

Device Functional Modes

Device Interface: Pin Description

• REFSEL (Input)

The REFSEL pin selects between the internal and external reference mode of the device.



If the REFSEL pin is set to logic high, then the internal reference is enabled and selected. If the REFSEL pin is set to logic low, then the internal reference circuit is disabled and powered down. In this mode, an external reference voltage must be provided to the REFIN/REFOUT pin.

The internal reference buffer is always enabled under both conditions.

The reference mode after power-up depends on the state of the REFSEL input pin.

RANGE (Input)

The RANGE pin selects input range for all analog input channels.

If this pin is set to logic high, the device is configured to operate in the ± 10 -V input range.

If this pin is set to logic low, the device is configured to operate in the \pm 5-V input range.

The RANGE pin is also used to put the device in standby or shutdown mode depending on the state of the STBY input pin, as explained in the Power-Down Modes section.

• STBY (Input)

The STBY pin puts the device into one of two power down modes: standby and power down.

If this pin is set to logic high, the device is in normal operation mode.

If this pin is set to logic low, the device is in standby or power down mode, depending on the state of RANGE pin.

In shutdown mode, all internal circuitry is powered down,

In standby mode, the internal reference remains powered up to enable a relatively quicker recovery to normal operation mode.

PAR/SER/BYTE SEL (Input)

The PAR/SER/BYTE SEL pin selects between the parallel, serial and parallel byte interface mode for reading data from the device.

If this pin is set to logic high, then the serial or parallel byte interface mode is selected depending on the state of DB15/BYTE SEL pin. If DB15/BYTE SEL pin is high, the parallel byte interface is selected, and if the DB15/BYTE SEL is low, then serial mode is selected.

CONVSTA, CONVSTB (Input)

CONVSTA, CONVSTB (Input) are conversion control input pins.

CONVSTA can be used to simultaneously sample and initiate the conversion process for the first half count of device input channels (channels 1-2), and CONVSTB can be used to simultaneously sample and initiate the conversion process for the latter half count of device input channels (channels 3-4).

On the rising edge of the CONVSTA, CONVSTB signals, the internal track-and-hold circuits for each analog input channel are placed into hold mode and the sampled input signal is converted.

The CONVSTA, CONVSTB signals can be pulled low when the internal conversion is over, as indicated by the BUSY signal. At this point, the front-end circuit for all analog input channels acquires the respective input signals and the internal ADC is not converting.

The output data can be read from the device irrespective of the status of the CONVSTA, CONVSTB pins.

RESET (Input)

The RESET pin can be used to reset the device at any time in an asynchronous manner. When the RESET pin is set to logic high, the device is in reset mode, and remains the state until the pin returns low. The device should be reset after power-up or recovery from shut down mode when all the supplies and



references have settled to the required accuracy.

RD/SCLK(Input)

RD/SCLK(Input) is dual function pin to be used in different interface mode.

Device operating condition	n	Functionality of RD/SCLK(Input)		
	PAR/SER/BYTE SEL=0	Active-low digital input pin to read the output data from the device. In parallel or parallel byte interface mode,		
Parallel interface	DB15/BYTE=0	the output bus is enabled when both the		
	PAR/SER/BYTE SEL=1	CS and RD inputs are tied to a logic low		
Parallel byte interface	DB15/BYTE=1	input.		
		External clock input for the serial data		
		interface. In serial mode, all synchronous		
		accesses to the device are timed with		
	PAR/SER/BYTE SEL=1	respect to the rising edge of		
Serial interface	DB15/BYTE=0	the SCLK signal.		

CS (Input)

The \overline{CS} pin is an active-low, chip-select signal.

A rising edge on the \overline{CS} signal outputs all the data lines in tri-state mode.

A falling edge of the \overline{CS} signal marks the beginning of the output data transfer frame in any interface mode of operation for the device.

OS[2:0]

The OS[2:0] pins are active-high digital input pins used to configure the oversampling ratio for the internal digital filter on the device.

When OS[2:0]=111, a higher filter bandwidth of ~30kHz is selected.

Device Modes of Operation

Power Down Modes

The device supports two power-down modes: standby mode and shutdown mode. The device can enter either power-down mode by pulling the $\overline{\text{STBY}}$ pin to a logic level. Additionally, the selection between these two power-down modes is done by the state of the RANGE pin.

Power Down Mode	STBY	Range		
Standby	0	1		
Shutdown	0	0		

Standby mode

In standby mode, only internal reference of the circuit is powered up, and analog front-end, signal-conditioning



circuit for each channel remains powered down.

Shutdown mode

In shutdown mode, the entire internal circuitry is powered down.

Conversion Control

The device offers precise control of simultaneously sampling all analog input channels.

Simultaneous Sampling on All Input Channels

All the analog input channels to be simultaneously sampled by connecting CONVSTA and CONVSTB signals together, and a single CONVST signal should be used to control the sampling of all analog input channels of the device.

Sampling of all input channels in Parallel Interface Timing Diagram

Simultaneous Sampling Two Sets of Input Channels

Two sets of analog input channels can be simultaneously sampled by separating CONVSTA and CONVSTB signals. And the device could not operate in oversampling mode in this state.

Data read operation

The device updates the internal data registers with the conversion data for all analog channels at the end of every conversion phase (when BUSY goes low).

If the output data are read after BUSY goes low, then the device outputs the conversion results for the current sample.

If the output data are read when BUSY is high, then the device outputs conversion result for the previous sample.

There are three interface mode:

Interface mode	PAR/SER/BYTE SEL	DB15/BYTE SEL		
Parallel interface	0	0		
Parallel byte interface	1	1		
Serial interface	1	0		

Parallel Data Read

The device supports a parallel interface mode for reading the device output data using the control inputs (\overline{CS} and \overline{RD}), the parallel output bus (DB[15:0]), and the BUSY indicator.

For applications that use only one device in the system and does not share the parallel output bus with any other devices, the \overline{CS} and \overline{RD} input signals can be tied together, or the \overline{CS} signal can be permanently tied low. At the first falling edge of the \overline{CS} and \overline{RD} signal, the output data of channel 1 becomes available on the parallel bus to be read by the digital host. At this instant the FRSTDATA output also goes high, indicating channel 1 data are ready to be read back. The output data for the remaining channels are clocked out on the parallel bus on subsequent falling edges of the \overline{CS} and \overline{RD} signal in a sequential manner.



For applications that use multiple devices in the system, the CS and RD input signals must be driven separately.

Parallel Byte Data Read

The parallel byte interface mode is very similar to the parallel interface mode, except that the output data for each channel is read in two data transfers of 8-bit byte sizes.

In parallel byte mode, the DB14/HBEN pin decides the order of most significant byte (MSB byte) and least significant byte (LSB byte). When DB14/HBEN pin is tied high, the MSB byte of the conversion results is output first followed by the LSB byte. This order is reversed when DB14/HBEN is tied to logic low. At the first falling edge of the \overline{RD} signal, the first byte of the channel 1 conversion result becomes available on DB[7:0]. This byte is followed by the second byte of conversion data on the next falling edge of the RD signal.

Serial Data Read

This interface mode uses a CS control input, a communication clock input (SCLK), BUSY and FRSTDATA output indicators, and serial data output lines DOUTA and DOUTB.

A total of 16 SCLK cycles are required to clock out 16 bits of conversion result for each channel and the same process can be repeated for the remaining channels in an ascending order.

The conversion results from the first set of channels appear first on DOUTA, followed by the second set of channels if only DOUTA is used for reading data. This order is reversed for DOUTB, in which the second set of channels appear first followed by the first set of channels. The use of both data output lines reduces the time needed for data retrieval and a higher throughput can therefore be achieved in this mode.

Data Read During Conversion

The device allows data read when and the ADC is converting and the BUSY output is high status. In this case, the ADC outputs conversion results for previous samples.

The data read back during conversion mode allows faster throughput to be achieved from the device.

Data Read During Conversion

The device can be configured in oversampling mode by the OS[2:0] pins. The input on the OS pins is latched on the falling edge of the BUSY signal to configure the oversampling rate for the next conversion.

In this mode, the CONVST A and CONVST B signals should be tied or driven together.

The BUSY signal duration varies with the OSR setting because the conversion time increases with OSR setting.

Oversampling the input signal reduces noise during the conversion process, thus reducing the histogram code spread for a dc input signal to the ADC.

TPAFE5161

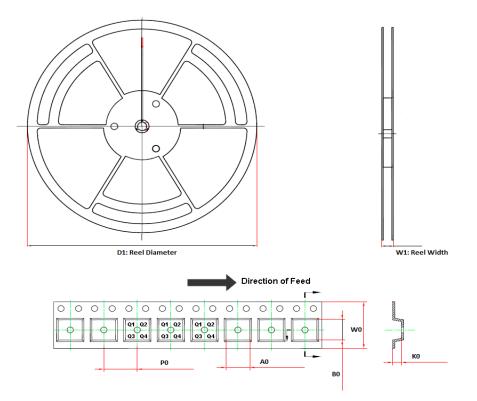




16bit, 4-Channel, Simultaneous Sampling ADC

with Bipolar inputs

Tape and Reel Information

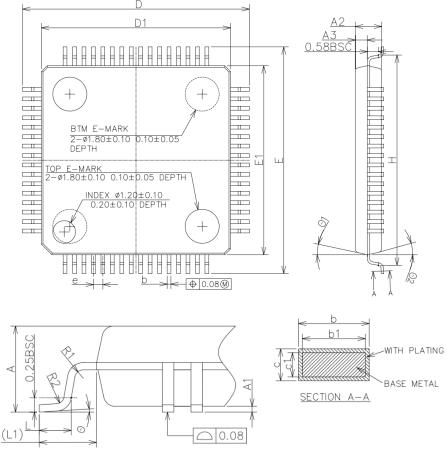


Order Number	Package	D1 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	W0 (mm)	Pin1 Quadrant
TPAFE5161SI04-QP7R	LQFP10X10-64	330	28.4	12.085	12.085	2.1	16	24	Q2



Package Outline Dimensions

LQFP10X10-64



LEAD FORM PART

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX		
А	—	—	1.60		
A1	0.05	—	0.15		
A2	1.35	1.40	1.45		
A3	0.59	0.64	0.69		
b	0.18	—	0.27		
b1	0.17	0.20	0.23		
С	0.13	—	0.18		
c1	0.117	0.127	0.137		
D	11.95	12.00	12.05		
D1	9.90	10.00	10.10		
E	11.95	12.00	12.05		
E1	9.90	10.00	10.10		
е	0.40	0.50	0.60		
Н	11.09	11.13	11.17		
L L1	0.53	—	0.70		
L1		1.00REF			
R1	0.15REF				
R2	0.13REF				
Θ	0°	3.5°	7°		
Θ1	11°	12°	13°		
Θ2	11°	12°	13°		



Order Information

Order Number	Operating Temperature Range	Package	Marking Information MSL		Transport Media, Quantity	Eco Plan	
TPAFE5161SI04-QP7R	-40 to 125	LQFP10X10-64	AFE5161	3	1000	Green	

Green: 3PEAK defines "Green" to mean RoHS compatible and free of halogen substances.

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